

## XPS Study of HfO<sub>2</sub> Growth on 2H-MoS<sub>2</sub> Substrate

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### Abstract

**The growth of high-k HfO<sub>2</sub> on 2H-MoS<sub>2</sub> substrate by plasma sputtering deposition is studied in-situ by x-ray photoelectron spectroscopy (XPS). It is found that plasma sputtering of Hf target in O<sub>2</sub> environment results in interface oxides formation i.e. MoO<sub>3</sub> and SO<sub>x</sub> (with 3.5<x<4). The functionalization of MoS<sub>2</sub> surface via oxide formation leads to pseudo layer-by-layer growth of HfO<sub>2</sub> thin film. The interface band alignment reveals a valence band offset of 1.3 eV and conduction band offset 3.3 eV at the HfO<sub>2</sub>/MoS<sub>2</sub> heterojunction.**

### 1. Introduction

Layered semiconductor MoS<sub>2</sub> has attracted increasing attention in field-effect transistors device application due to its mobility can be enhanced by dielectric engineering. In compared to electron mobility of n-type bulk MoS<sub>2</sub> in the 50-200 cm<sup>2</sup>V<sup>-1</sup>s<sup>-1</sup> range [1] at room temperature and monolayer MoS<sub>2</sub> of ~1 cm<sup>2</sup> V<sup>-1</sup> s<sup>-1</sup> (in air/MoS<sub>2</sub>/SiO<sub>2</sub> structures) [2], mobility enhancement is seen when monolayer and multilayers MoS<sub>2</sub> is coupled with high dielectric constant (high-k) materials. For examples, HfO<sub>2</sub>/monolayer MoS<sub>2</sub> and PMMA/multilayers MoS<sub>2</sub> register electron mobility of 200cm<sup>2</sup>V<sup>-1</sup>s<sup>-1</sup> [3] and 470cm<sup>2</sup>V<sup>-1</sup>s<sup>-1</sup> [4], respectively. To realize the full potential of the high-k/MoS<sub>2</sub> heterojunction, however, demands fundamental understanding of the growth process and the resultant process-dependent heterojunction properties. ALD depositions of HfO<sub>2</sub> on pristine MoS<sub>2</sub> have resulted in island-growth [5-6], which is unfavorable for transistor that demands sharp interface. Interface band alignment of MoS<sub>2</sub> and HfO<sub>2</sub> is also an important aspect of heterojunction performance i.e. barrier height and contact resistance, which affects junction leakage current and charge injection. Most of these studies are also theoretical rather than experimental. To address these research gaps, this work investigates the growth of HfO<sub>2</sub> on pristine, bulk 2H-MoS<sub>2</sub> by using magnetron plasma sputtering. By depositing at various time intervals on a single sample, the interface chemistry, HfO<sub>2</sub> thin film growth mode and HfO<sub>2</sub>/MoS<sub>2</sub> band alignment have been elucidated with the aid of XPS.

### 2. Methodology

X-ray photoemission spectroscopy (XPS) technique has been employed (VG ESCALAB 200i-XL) to study the interface chemistry and band alignment measurement. The XPS is equipped with a monochromatic Al K $\alpha$  (1486.6eV) x-ray source and the binding energy (BE) is calibrated by using pure nickel (Ni), gold (Au), silver (Ag), and copper (Cu) standard samples by setting the Ni Fermi edge, Au 4f<sub>7/2</sub>, Ag 3d<sub>5/2</sub>, and Cu 2p<sub>3/2</sub> peaks at BE of 0.00 $\pm$ 0.02, 83.98 $\pm$ 0.02, 368.26 $\pm$ 0.02, and 932.67 $\pm$ 0.02 eV, respectively.

Commercially available 2H-MoS<sub>2</sub> (*Burleigh Inst.*) is in-situ annealed to 500°C to remove surface carbon and oxygen contaminations to below XPS detection limits which qualifies the sample surface cleanliness. Deposition of HfO<sub>2</sub> film onto MoS<sub>2</sub> substrate is conducted in-situ by Ar<sup>+</sup> plasma sputtering of Hf metal target which oxidizes in oxygen environment. Different thicknesses of HfO<sub>2</sub> thin film have been grown on MoS<sub>2</sub> up to ~5.5nm. By analyzing the sample surface core-level and valence band photoelectron signals at the pause of each growth interval with XPS, the interface chemical reactions and band alignment are elucidated and resolved in a manner of increasing overlayer thickness.

### 3. Results and discussions

The deposition of HfO<sub>2</sub> by plasma sputtering has resulted in various interface oxides formation. The analysis of high resolution core-level spectra of Mo 3d, S 2p, Hf 4f and O 1s based on BE positions suggests interface MoO<sub>3</sub> and sulphates/sulphites SO<sub>x</sub> (with 3.5<x<4) formations. XPS quantitative analysis confirms the identified species of HfO<sub>2</sub>, MoO<sub>3</sub> and SO<sub>x</sub>. The formation of oxides and sulphates/sulphites can be attributed to O radical reaction with the MoS<sub>2</sub> substrate during the deposition.

Composition plot of MoS<sub>2</sub> and MoO<sub>3</sub> with respect to HfO<sub>2</sub> indicate exponential-like signals decay of the substrate and MoO<sub>3</sub>. This is indicative of pseudo layer-by-layer growth mode of the HfO<sub>2</sub> thin film. The plot is well fitted with pseudo-layer-by-layer growth model [7] (see Fig. 1). The atomic fractions of substrate MoS<sub>2</sub> (Mo 3d<sub>5/2</sub>) is found using the equation (1),

$$C_{Mo}(t) = \frac{100 \times \exp\left(\frac{-Gt}{\lambda_{3d_{5/2}}^{Mo}}\right)}{\exp\left(\frac{-Gt}{\lambda_{3d_{5/2}}^{Mo}}\right) + K \times \left[1 - \exp\left(\frac{-Gt}{\lambda_{4f_{7/2}}^{Hf}}\right)\right]} \quad (1)$$

and for the atomic fraction of Hf we have

$$C_{Hf}(t) = \frac{100 \times \left[1 - \exp\left(\frac{-Gt}{\lambda_{4f_{7/2}}^{Hf}}\right)\right]}{\frac{1}{K} \exp\left(\frac{-Gt}{\lambda_{3d_{5/2}}^{Mo}}\right) + \left[1 - \exp\left(\frac{-Gt}{\lambda_{4f_{7/2}}^{Hf}}\right)\right]} \quad (2)$$

where  $K = \frac{I_{Hf}^{\infty} S_{3d_{5/2}}^{Mo} T_{3d_{5/2}}^{Mo}}{I_{Mo}^0 S_{4f_{7/2}}^{Hf} T_{4f_{7/2}}^{Hf}}$  is a constant since  $S_{3d_{5/2}}^{Mo}$ ,  $T_{3d_{5/2}}^{Mo}$ ,  $S_{4f_{7/2}}^{Hf}$  and  $T_{4f_{7/2}}^{Hf}$  are the sensitivity factors and instrumental transmission factor associated with detecting Mo 3d<sub>5/2</sub> and Hf 4f<sub>7/2</sub> XPS peaks, respectively, while  $I_{Mo}^0$  and  $I_{Hf}^{\infty}$  are the XPS intensities of the clean MoS<sub>2</sub> substrate (before deposition) and HfO<sub>2</sub> bulk layers, respectively. These values are determined experimentally.

The band alignment of bulk MoS<sub>2</sub> and bulk HfO<sub>2</sub> is obtained from direct measurements of the valence band edges (see Fig. 2). We obtained valence band offset (VBO) of 1.3eV and conduction band offset (CBO) of 3.3eV between MoS<sub>2</sub> and HfO<sub>2</sub>. During the growth, we observe a 0.4eV shift in MoS<sub>2</sub> core-levels which is explained as internal built-in field at the junctions of HfSO<sub>x</sub>/MoS<sub>2</sub> and/or MoO<sub>3</sub>/MoS<sub>2</sub>. As no further shift is observed after initial deposition, we conclude that no interface band bending has taken place.

#### 4. Conclusions

In conclusion, plasma sputter deposition is a viable method to grow sharp HfO<sub>2</sub>/MoS<sub>2</sub> interface. It is a single-step functionalization-and-growth of HfO<sub>2</sub> on MoS<sub>2</sub> using plasma sputtering. We elucidate the deposition mechanisms from the interface interactions and found O<sub>2</sub> to be reacting with the MoS<sub>2</sub> substrate, resulting in MoO<sub>3</sub> and SO<sub>x</sub> formation which helps to support layer-by-layer growth of HfO<sub>2</sub>, as evidenced by curve-fitting XPS composition plot with pseudo-layer-by-layer growth model. Valence band structure probed by XPS suggest the HfO<sub>2</sub>/MoS<sub>2</sub> VBO and CBO are 1.3 and 3.3eV, respectively. No band bending has been observed near the overlayer/MoS<sub>2</sub> interface during the deposition process.

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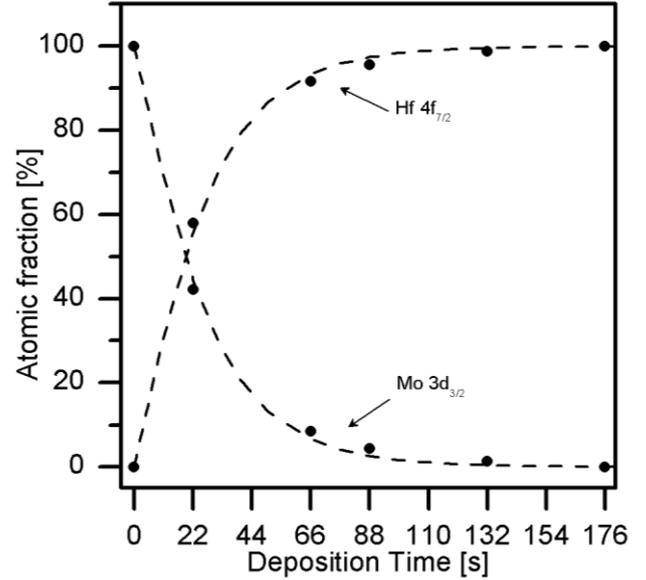


Fig. 1 Exponential-like XPS composition evolution of Mo 3d<sub>3/2</sub> (MoS<sub>2</sub>) and Hf 4f<sub>7/2</sub> (HfO<sub>2</sub>) suggest layer-by-layer growth of HfO<sub>2</sub> thin film.

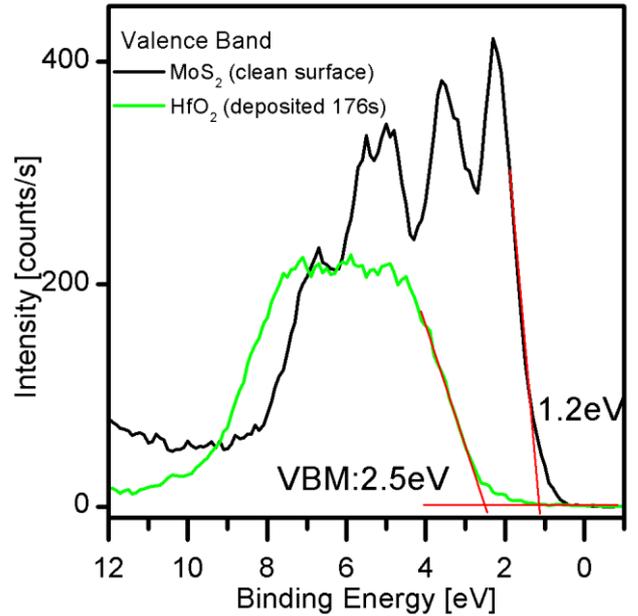


Fig. 2 Bulk MoS<sub>2</sub> and HfO<sub>2</sub> valence band structure and edges at 1.2eV and 2.5eV, respectively, result in valence band offset of 2.5-1.2=1.3eV at HfO<sub>2</sub>/MoS<sub>2</sub> interface.